

Please note that Cypress is an Infineon Technologies Company.

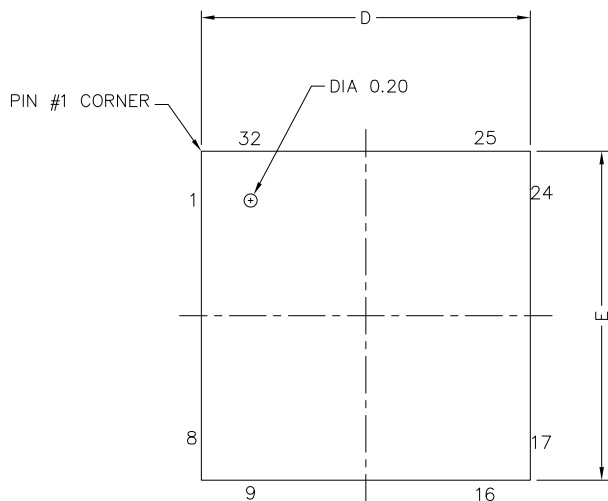
The document following this cover page is marked as “Cypress” document as this is the company that originally developed the product. Please note that Infineon will continue to offer the product to new and existing customers as part of the Infineon product portfolio.

Continuity of document content

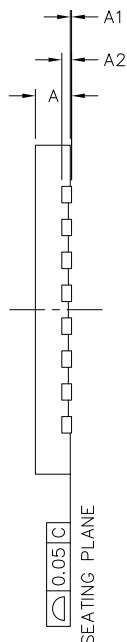
The fact that Infineon offers the following product as part of the Infineon product portfolio does not lead to any changes to this document. Future revisions will occur when appropriate, and any changes will be set out on the document history page.

Continuity of ordering part numbers

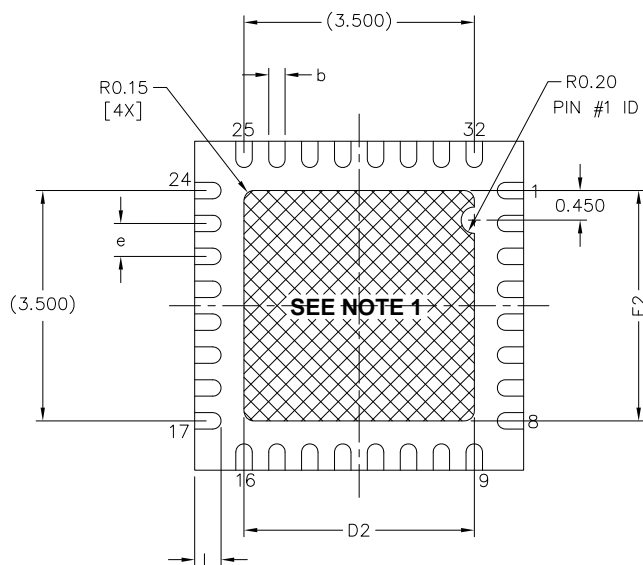
Infineon continues to support existing part numbers. Please continue to use the ordering part numbers listed in the datasheet for ordering.



TOP VIEW



SIDE VIEW



BOTTOM VIEW

SYMBOL	DIMENSIONS		
	MIN.	NOM.	MAX.
A	0.50	0.55	0.60
A1	-	0.020	0.045
A2	0.15 BSC		
D	4.90	5.00	5.10
D2	3.40	3.50	3.60
E	4.90	5.00	5.10
E2	3.40	3.50	3.60
L	0.30	0.40	0.50
b	0.18	0.25	0.30
e	0.50 TYP		

NOTES:

1. HATCH AREA IS SOLDERABLE EXPOSED PAD
2. BASED ON REF JEDEC # MO-248
3. PACKAGE WEIGHT: 0.0388g
4. DIMENSIONS ARE IN MILLIMETERS

REVISIONS			
Rev	ECN No.	Orig. of change	Reason for Revision
**	1772385	-	NEW RELEASE
*A	2287286	-	REVISED LEAD WIDTH FROM 0.23 +0.05/-0.07 TO 0.23 +/-0.05. DELETED SUBCON NAME ON TITLE. REVISED EPAD SIZE FROM 3.55X3.55 TO 3.5X3.5
*B	2515796	-	UPDATED SPEC. TITLE AND DIMENSION FORMAT
*C	2599714	-	REVISED DWG AND CORRECTION PER DIMENSION
*D	2818637	-	CHANGE TEMPLATE, CHANGE TITLE FROM 32L QFN 5 X 5 X 0.55MM PACKAGE OUTLINE 3.5 X 3.5 EPAD (SAWN TYPE) TO PACKAGE OUTLINE, 32L QFN 5X5X0.55 MM LQ32 3.5X3.5 EPAD (SAWN)
*E	3818021	XANC	Updated document template to align with spec. 001-82380.
*F	5744799	KOTA	Convert to new drawing format. Add package code LQ32B.

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PACKAGE
CODE(S)

LQ32

LQ32B

DRAWN BY
KOTA
APPROVED BY
JVP

DATE
22-MAY-17
DATE
22-MAY-17



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TITLE PACKAGE OUTLINE, 32 LEAD QFN 5.0X5.0X0.55 MM
LQ32/LQ32B, 3.5X3.5 MM EPAD (SAWN)

SPEC NO. 001-42168

REV
*F

SCALE : TO FIT

SHEET 2 OF 2